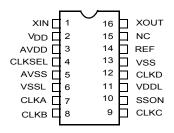


### **Pin Configuration**

Figure 1. 16-pin TSSOP pinout



#### **Pin Definitions**

Pin Name	Pin Number	Description	
XIN	1	Reference input Or crystal input	
VDD	2	3.3 V voltage supply	
AVDD	3	3.3 V analog voltage	
CLKSEL	4 (-21)	0 = 33.33 MHz out, 1 = 25 MHz Out. Weak pull-up.	
AVSS	5	Analog ground	
VSSL	6	K ground	
CLK(A:D)	7, 8, 9, 12	ock outputs at V <sub>DDL</sub> level	
SSON	10	oread spectrum enable pin 0 = SS off; 1 = SS on. Weak pull-up.	
VDDL	11	V clock voltage supply	
VSS	13	Ground	
REF	14	ference output at V <sub>DD</sub> level	
NC	15	o connect	
XOUT <sup>[1]</sup>	16	Crystal output	

#### Notes

Float XOUT if XIN is externally driven.



### **Maximum Ratings**

Exceeding maximum ratings may impair the useful life of the device. These user guidelines are not tested.

Supply voltage $(V_{DD}, AV_{DD}, V_{DDL})$	–0.5 to +7.0 V
DC input voltage	–0.5 V to V <sub>DD</sub> + 0.5 V

Storage temperature	
(Non-condensing)	–55 °C to +125 °C
Junction temperature	–40 °C to +125 °C
Data retention at Tj = 125 °C	> 10 years
Package power dissipation	350 mW
Static discharge voltage (per MIL-STD-883, Method 3015)	≥ 2000 V

### **Recommended Operating Conditions**

Parameter	Description	Min	Тур	Max	Unit
$V_{DD,} AV_{DD}$	Supply voltage	3.135	3.30	3.465	V
$V_{DDL}$	Supply voltage for CLK (A-D)	3.135	3.30	3.465	V
T <sub>A</sub>	Ambient temperature (industrial temp grade)	-40	-	85	°C
C <sub>LOAD</sub>	Max. output load capacitance	-	-	15	pF
F <sub>ref</sub>	Reference frequency	-	25	-	MHz

# **Crystal Specification**

Parameter [2]	Description	Min	Тур	Max	Unit
CR <sub>load</sub>	Crystal load capacitance (-21)	_	15	_	pF
ESR	Equivalent series resistance	_	_	50	Ω

### **DC Electrical Specifications**

Parameter	Description	Condition	Min	Тур	Max	Unit
I <sub>OH</sub>	Output high current	$V_{OH} = V_{DD} - 0.5 \text{ V}, V_{DD}/V_{DDL} = 3.3 \text{ V}$	12	24	_	mA
I <sub>OL</sub>	Output low current	V <sub>OL</sub> = 0.5 V, V <sub>DD</sub> /V <sub>DDL</sub> = 3.3 V	12	24	_	mA
I <sub>IH</sub>	Input high current	$V_{IH} = V_{DD}$	_	5	10	μΑ
I <sub>IL</sub>	Input low current	V <sub>IL</sub> = 0 V	_	_	50	μΑ
V <sub>IH</sub>	Input high voltage	CMOS levels	0.7 × V <sub>DD</sub>	-	_	V
V <sub>IL</sub>	Input low voltage	CMOS levels	_	_	0.3 × V <sub>DD</sub>	V
C <sub>IN</sub> [3]	Input capacitance	Input pins excluding XIN	_	_	7	pF
R <sub>UP</sub> <sup>[3]</sup>	Pull-up resistor on input pins	$V_{DD}$ = 3.14 to 3.47 V, measured at $V_{IN}$ = 0 V	80	100	150	kΩ
I <sub>DD</sub>	Supply current	AV <sub>DD</sub> /V <sub>DD</sub> /V <sub>DDL</sub> Current.	_	42	60	mA

#### **Thermal Resistance**

Parameter [3]	Description	Test Conditions	16-pin TSSOP	Unit
$\theta_{JA}$		Test conditions follow standard test methods and procedures for measuring thermal impedance, in		°C/W
$\theta_{JC}$	Thermal resistance (junction to case)	accordance with EIA/JESD51.	14	°C/W

#### Notes

- A fundamental parallel resonant crystal must be used.
   Guaranteed by Characterization, not 100% tested.
   These parameters are guaranteed by design and are not tested.

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### **AC Electrical Specifications**

Parameter [4]	Description	Condition	Min	Тур	Max	Unit
DC	Output duty cycle	Duty Cycle is defined in Figure 2, 50% of V <sub>DD</sub>	45	50	55	%
ER	Rising edge rate	Output clock edge rate, measured from 20% to 80% of $V_{DD}$ , $C_{LOAD}$ = 15 pF. See Figure 3.	0.8	1.4	_	V/ns
EF	Falling edge rate	Output clock edge rate, measured from 80% to 20% of $V_{DD}$ , $C_{LOAD}$ = 15 pF. See Figure 3.	0.8	1.4	_	V/ns
tj	RMS clock cycle-to-cycle Jitter	RMS cycle-to-cycle jitter with spread on. Measured at V <sub>DD</sub> /2.	_	15	40	ps

### **Voltage and Timing Definitions**

Figure 2. Duty Cycle Definition

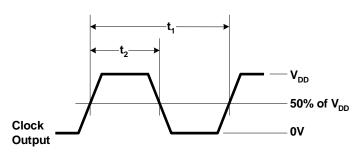
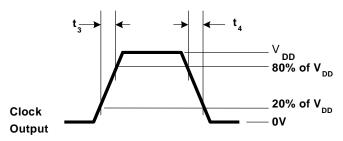


Figure 3. ER = (0.6 ×  $V_{DD}$ ) /t<sub>3</sub>, EF = (0.6 ×  $V_{DD}$ ) /t<sub>4</sub>



#### Notes

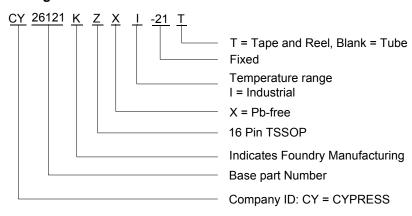
<sup>4.</sup> Guaranteed by Characterization, not 100% tested.



### **Ordering Information**

Ordering Code	Package Type	Operating Range
CY26121KZXI-21	16-pin TSSOP	Industrial, –40 °C to 85 °C
CY26121KZXI-21T	16-pin TSSOP – Tape and Reel	Industrial, –40 °C to 85 °C

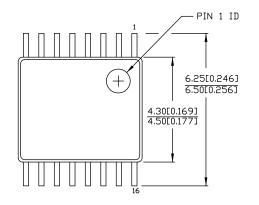
#### **Ordering Code Definitions**





### **Package Drawing and Dimensions**

Figure 4. 16-pin TSSOP (4.40 mm Body) Z16.173/ZZ16.173 Package Outline, 51-85091

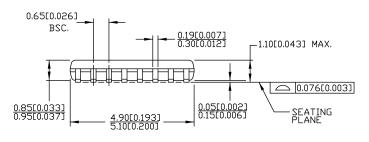


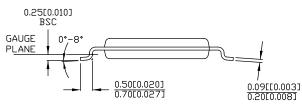
DIMENSIONS IN MMCINCHES) MIN. MAX.

REFERENCE JEDEC MO-153

PACKAGE WEIGHT 0.05gms

PART #		
Z16.173	STANDARD PKG.	
ZZ16.173	LEAD FREE PKG.	





51-85091 \*E



### **Acronyms**

Table 1. Acronyms Used in this Document

Acronym	Description	
ESR	Equivalent Series Resistance	
PLL	Phase-Locked Loop	
TSSOP	Thin-Shrunk Small Outline Package	

### **Document Conventions**

#### **Units of Measure**

Table 2. Units of Measure

Symbol	Unit of Measure
°C	degree Celsius
kΩ	kilohm
MHz	megahertz
μΑ	microampere
mA	milliampere
mW	milliwatt
ns	nanosecond
Ω	ohm
%	percent
pF	picofarad
ps	picosecond
V	volt



# **Document History Page**

Davi	CON No	Janua Data	Orig. of	Description of Change
Rev.	ECN No.	Issue Date	Change	Description of Change
**	121669	02/11/03	CKN	New data sheet.
*A	2440886	See ECN	KVM / AESA	Updated Ordering Information: Added part numbers CY26121ZXC-21, CY26121ZXC-21T, CY26121ZXI-21, and CY26121ZXI-21T. Added part numbers CY26121KZC-21, CY26121KZC-21T, CY26121KZI-21, and CY26121KZI-21T. Added part numbers CY26121KZXC-21, CY26121KZXC-21T, CY26121KZXI-21T, CY26121KZXI-21, and CY26121KZXI-21T. Removed part numbers CY26121KZXI-21T. Removed part numbers CY26121ZI-11, CY26121ZI-11T, CY26121ZI-31 and CY26121ZI-31T. Added Note "Not recommended for new designs." and referred in some MPNs Updated to new template.
*B	2899683	03/26/10	KVM	Removed reference to -2, -3, -11, -31 parts in all instances across the document. Updated Ordering Information: Removed inactive parts. Removed Note "Not recommended for new designs." and its references. Updated Package Drawing and Dimensions.
*C	3383431	09/26/2011	PURU	Updated Logic Block Diagram. Added Ordering Code Definitions under Ordering Information. Updated Package Drawing and Dimensions. Added Acronyms and Units of Measure.
*D	4556342	10/30/2014	TAVA	Updated Package Drawing and Dimensions: spec 51-85091 – Changed revision from *C to *E. Updated to new template. Completing Sunset Review.
*E	5279177	05/20/2016	PSR	Added Thermal Resistance. Updated to new template.



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